

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc2870iufd#trpbf

(Engineering Calculation)

QFN 4mm X 5mm Exp. Pad

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**TOTAL MASS (g) : 0.051027**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003892	1000000	76273.03125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.019997	975000	391888.96875		
		Iron (Fe)	7439-89-6	0.000492	24000	9641.91601562		
		Phosphorus (P)	7723-14-0	0.000006	300	117.584327698		
		Zinc (Zn)	7440-66-6	0.000014	700	274.363433838		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.020509</b>	<b>1000000</b>	<b>401922.84375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000227	1000000	4452.68310547		
		<b>External Plating Total:</b>				<b>0.000227</b>	<b>1000000</b>	<b>4452.68310547</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000429	1000000	8407.28027344		
<b>Internal Plating Total:</b>				<b>0.000429</b>	<b>1000000</b>	<b>8407.28027344</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000593	800000	11621.2509766		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000148	200000	2900.41357422		
<b>Die Attach Total:</b>				<b>0.000741</b>	<b>1000000</b>	<b>14521.6640625</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.003244	130000	63573.9257812		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.021457	860000	420501.15625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000250	10000	4899.34716797		
		<b>Encapsulation Total:</b>				<b>0.024951</b>	<b>1000000</b>	<b>488974.4375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000278	1000000	5448.07373047		
					<b>TOTAL MASS (g) :</b>	<b>0.051027</b>		